2SD1133, 2SD1134

Silicon NPN Triple Diffused

HITACHI

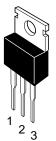
ADE-208-905 (Z) 1st. Edition Sep. 2000

Application

Low frequency power amplifier complementary pair with 2SB857 and 2SB858

Outline

TO-220AB



- 1. Base
- Collector (Flange)
- 3. Emitter

Absolute Maximum Ratings (Ta = 25°C)

		Ratings		
Item	Symbol	2SD1133	2SD1134	Unit
Collector to base voltage	V_{CBO}	70	70	V
Collector to emitter voltage	V _{CEO}	50	60	V
Emitter to base voltage	V_{EBO}	5	5	V
Collector current	I _c	4	4	A
Collector peak current	I _{C(peak)}	8	8	A
Collector power dissipation	P _c *1	40	40	W
Junction temperature	Tj	150	150	°C
Storage temperature	Tstg	-45 to +150	-45 to +150	°C

Note: 1. Value at $T_c = 25$ °C.



2SD1133, 2SD1134

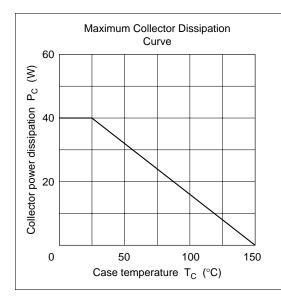
Electrical Characteristics ($Ta = 25^{\circ}C$)

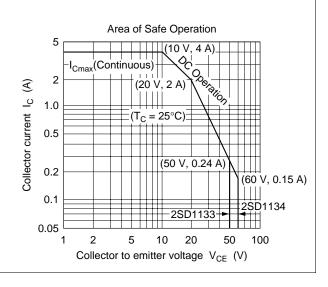
		2SD1	133		2SD1134				
Item	Symbol	Min	Тур	Max	Min	Тур	Max	Unit	Test conditions
Collector to base breakdown voltage	$V_{(BR)CBO}$	70	_	_	70	_	_	V	$I_{\rm C} = 10 \ \mu \text{A}, \ I_{\rm E} = 0$
Collector to emitter breakdown voltage	$V_{(BR)CEO}$	50	_	_	60	_	_	V	$I_{\rm C}$ = 50 mA, $R_{\rm BE}$ = ∞
Emitter to base breakdown voltage	$V_{(BR)EBO}$	5	_	_	5	_	_	V	$I_E = 10 \mu A, I_C = 0$
Collector cutoff current	I _{CBO}	_	_	1	_	_	1	μΑ	$V_{CB} = 50 \text{ V}, I_{E} = 0$
DC current transfer ratio	h _{FE1} *1	60	_	320	60	_	320		$V_{CE} = 4V I_{C} = 1 A^{*2}$
	h _{FE2}	35	_	_	35	_	_		$I_{\rm C} = 0.1 A^{*2}$
Collector to emitter saturation voltage	$V_{CE(sat)}$	_	_	1	_	_	1	V	$I_{\rm C} = 2 \text{ A}, I_{\rm B} = 0.2 \text{ A}^{*2}$
Base to emitter voltage	V _{BE}	_	_	1	_	_	1	V	$V_{CE} = 4 \text{ V}, I_{C} = 1 \text{ A}^{*2}$
Gain bandwidth product	f _T	_	7	_	_	7	_	MHz	$V_{CE} = 4 \text{ V}, I_{C} = 0.5 \text{ A}^{*2}$

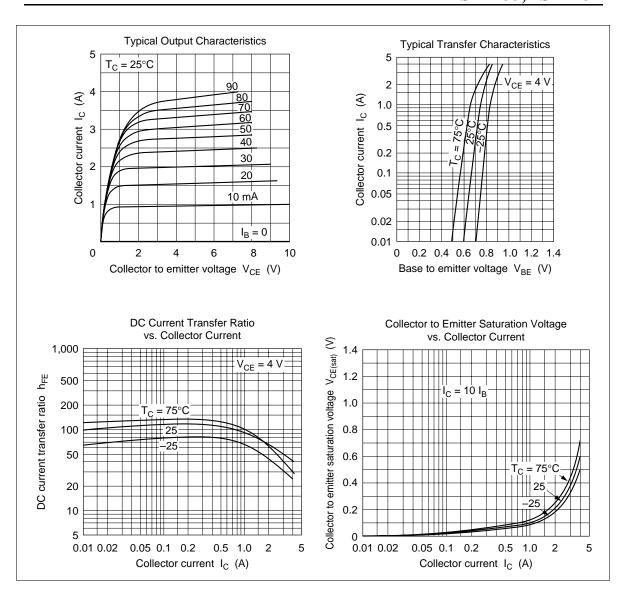
Notes: 1. The 2SD1133 and 2SD1134 are grouped by h_{FE1} as follows.

2. Pulse test.

В	С	D
60 to 120	100 to 200	160 to 320

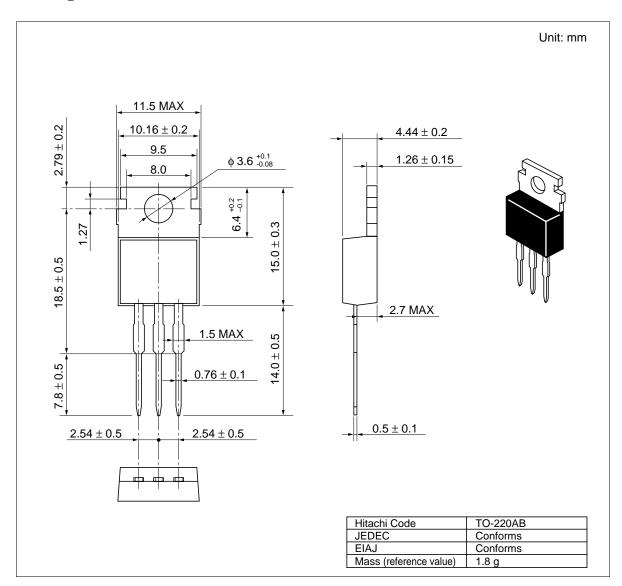






2SD1133, 2SD1134

Package Dimensions



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